

H5N3004P

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1111-0100

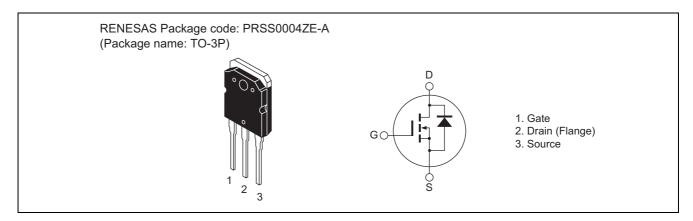
(Previous: ADE-208-1523)

Rev.1.00 Sep 07, 2005

Features

- Low on-resistance
- Low leakage current
- High speed switching
- Low gate charge (Qg)
- Avalanche ratings

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	300	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I _D	25	Α
Drain peak current	I _{D (pulse)} Note 1	100	Α
Body-drain diode reverse drain current	I _{DR}	25	Α
Body-drain diode reverse drain peak current	I _{DR (pulse)} Note 1	100	Α
Avalanche current	I _{AP} Note 3	25	Α
Channel dissipation	Pch Note 2	150	W
Channel to case thermal Impedance	θ ch-c	0.833	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at Tc = 25°C

3. Tch ≤ 150°C

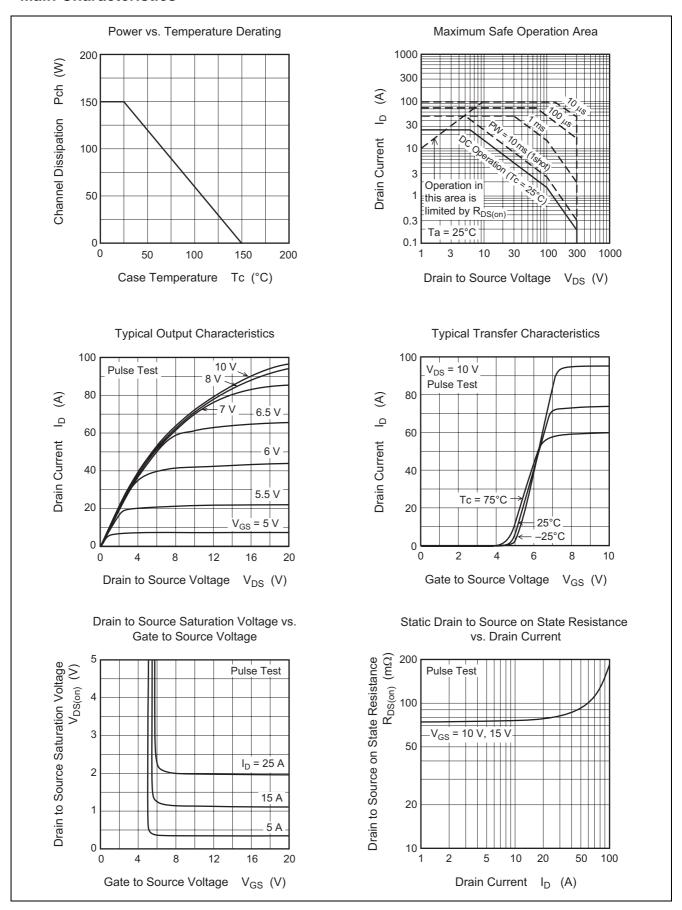
Electrical Characteristics

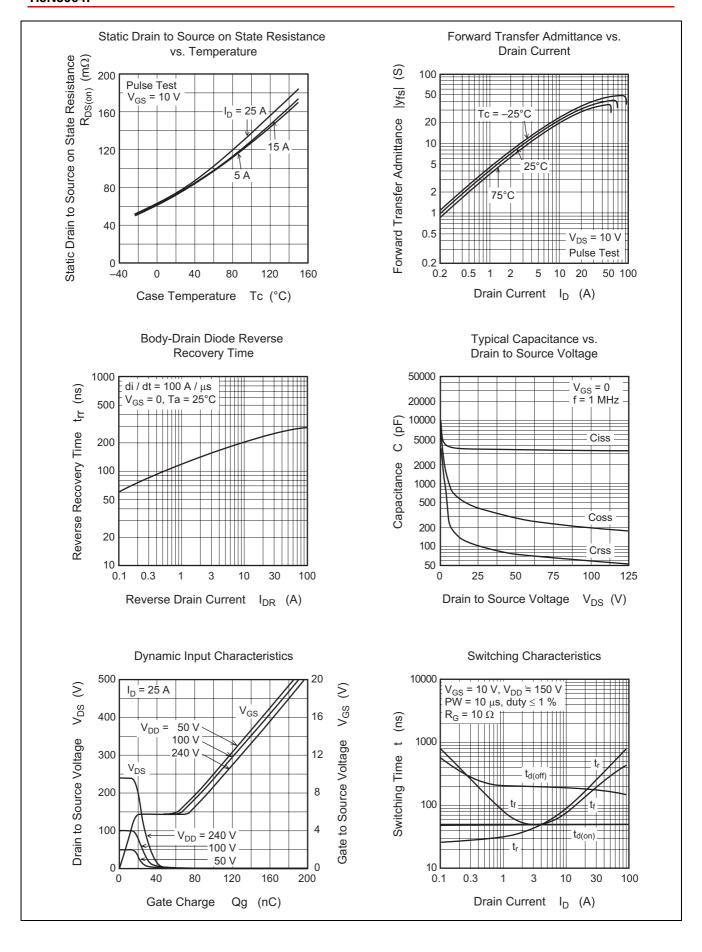
 $(Ta = 25^{\circ}C)$

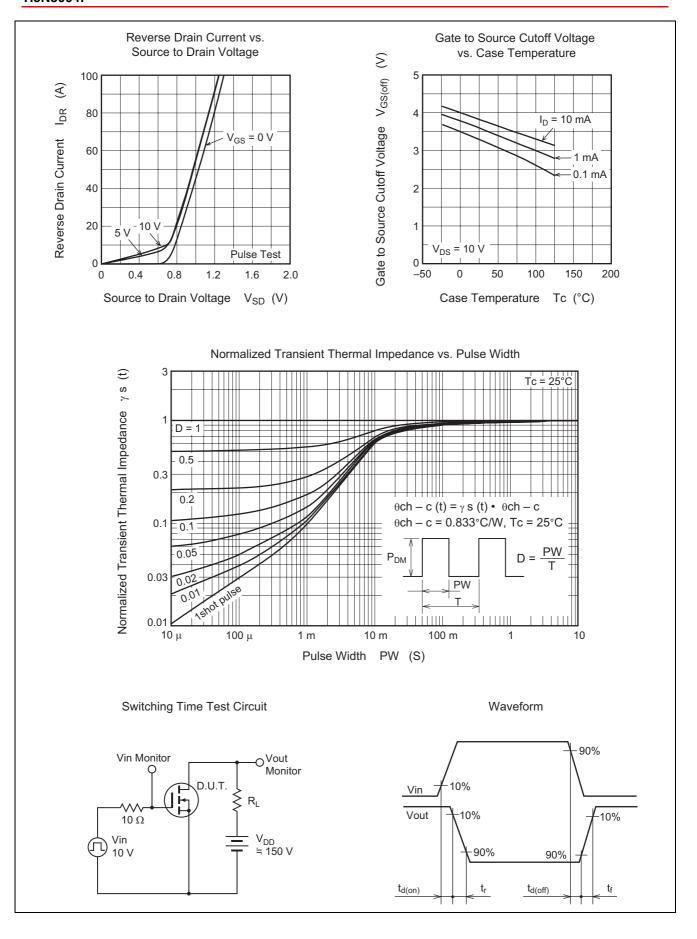
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	300	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I _{DSS}	I	_	1	μΑ	$V_{DS} = 300 \text{ V}, V_{GS} = 0$
Gate to source leak current	I_{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS (off)}$	3.0	_	4.0	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward transfer admittance	y _{fs}	15	25	_	S	$I_D = 12.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 4}}$
Static drain to source on state resistance	R _{DS (on)}	I	0.076	0.093	Ω	$I_D = 12.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	3600	_	pF	V _{DS} = 25 V
Output capacitance	Coss	_	400	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	100	_	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	50	_	ns	I _D = 12.5 A
Rise time	t _r	_	120	_	ns	$R_L = 12 \Omega$
Turn-off delay time	t _{d (off)}	_	180	_	ns	V _{GS} = 10 V
Fall time	t _f	_	90	_	ns	$Rg = 10 \Omega$
Total gate charge	Qg	_	110	_	nC	V _{DD} = 240 V
Gate to source charge	Qgs	_	18	_	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	_	55	_	nC	I _D = 25 A
Body-drain diode forward voltage	V_{DF}	_	0.9	1.35	V	I _F = 25 A, V _{GS} = 0
Body-drain diode reverse recovery time	t _{rr}		250	_	ns	I _F = 25 A, V _{GS} = 0
Body-drain diode reverse recovery charge	Q _{rr}	_	2.3		μС	di _F /dt = 100 A/μs

Note: 4. Pulse test

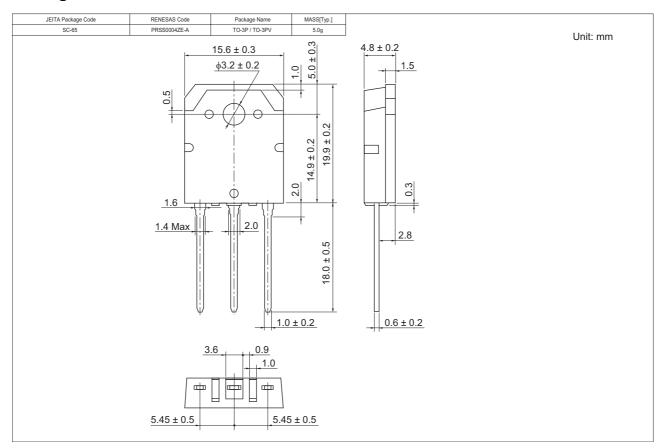
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
H5N3004P-E	360 pcs	Box (Tube)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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